

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

18.03.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-070my 330x490mm	50200246	70	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		2		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3		
		70	L2			
C-STD-FR4-ML-0.203mm-070+070-TG150-H...	50203119	203		4	A00	B00
		70	L3			
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6		
A-RS Kupferfolie-070my 330x490mm	50200246	70	RS	7		

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

911 µm

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